

MakB2 1
2 4. (Amended) The chip carrier according to claim 1 further
3 comprising an upper surface and wherein the outer well has a first base and the inner well
4 has a second base wherein there is a first distance between the first base and the upper
5 surface and there is a second distance between the second base and the upper upper
6 surface, the first distance greater than the second distance [extends farther away from the
upper surface than the inner well].

J 1 5. (Amended) The chip carrier according to claim 1 further
2 comprising an integrated circuit removably positioned on the base.

C 1 6. (Amended) The chip carrier according to claim 1 wherein the
2 outer well and the inner well encircle the base [are continuous].

C 1 7. (Amended) The chip carrier according to claim 1 wherein at
2 least one of the outer well and the inner well encircle the base [are not continuos].

3 1 21. (Newly Added) The chip carrier according to claim 1 further
2 comprising:
3 an upper surface;
4 an integrated circuit positioned on the base and below the upper surface,
5 the integrated circuit having leads;
6 wherein the inner well has a base, the leads positioned above the base and
7 below the upper surface.

A 1 22. (Newly Added) The chip carrier according to claim 1
2 wherein the base, the inner well, and the outer well form an integrated circuit carrier and
3 the chip carrier further comprises a plurality of integrated circuit carriers.

1 23. (Newly Added) The chip carrier according to claim 1 further
2 comprising a cover adapted to hold an integrated circuit in the chip carrier.

1 24. (Newly Added) The chip carrier according to claim 1 further
2 comprising a cover for holding an integrated circuit in the chip carrier.

2 MakB3 1 25. (Newly Added) A chip carrier comprising:
2 a base,
3 an inner well formed about the periphery of the base; and

~~an outer well formed about the periphery of the inner well,~~

the chip carrier adapted to temporarily hold an integrated circuit.

26. (Newly Added) The chip carrier according to claim 25 wherein the base, the inner well, and the outer well form an integrated circuit carrier and the chip carrier further comprises a plurality of integrated circuit carriers.

27. (Newly Added) The chip carrier according to claim 25 further comprising a cover adapted to hold an integrated circuit in the chip carrier.

28. (Newly Added) The chip carrier according to claim 25 further comprising a cover for holding an integrated circuit in the chip carrier.